

AO3401A

30V P-Channel MOSFET

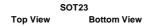
General Description

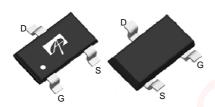
The AO3401A uses advanced trench technology to provide excellent $R_{\rm DS(ON)}$, low gate charge and operation gate voltages as low as 2.5V. This device is suitable for use as a load switch or other general applications.

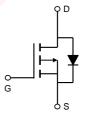
Product Summary

 $\begin{array}{lll} V_{DS} & -30V \\ I_D & (at \ V_{GS} \!\!=\! \!\!-\! 10V) & -4.0A \\ R_{DS(ON)} & (at \ V_{GS} \!\!=\! \!\!\!-\! 10V) & < 50m\Omega \\ R_{DS(ON)} & (at \ V_{GS} \!\!=\! \!\!\!\!-\! 4.5V) & < 60m\Omega \\ R_{DS(ON)} & (at \ V_{GS} \!\!=\! \!\!\!\!\!-\! 2.5V) & < 85m\Omega \end{array}$









Absolute Maximum Ratings T_A=25℃ unless otherwise noted

Parameter		Symbol	Maximum	Units	
Drain-Source Voltage		V _{DS}	-30	V	
Gate-Source Voltage		V _{GS}	±12	V	
Continuous Drain	T _A =25℃		-4		
Current	T _A =70℃	'D	-3.2	A	
Pulsed Drain Current ^c		I _{DM}	-27		
	T _A =25℃	D	1.4	W	
Power Dissipation ^B	wer Dissipation B T_{A} =70 C		0.9	VV	
Junction and Storage Temperature Range		T _J , T _{STG}	-55 to 150	C	

Thermal Characteristics								
Parameter	Symbol	Тур	Max	Units				
Maximum Junction-to-Ambient A	t ≤ 10s		70	90	℃/W			
Maximum Junction-to-Ambient AD	Steady-State	$R_{\theta JA}$	100	125				
Maximum Junction-to-Lead Steady-State		$R_{\theta JL}$	63	80	℃/W			



Electrical Characteristics (T_J=25℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
STATIC P	ARAMETERS					
BV _{DSS}	Drain-Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-30V, V _{GS} =0V			-1	
		T _J =55℃			-5	μΑ
I_{GSS}	Gate-Body leakage current	V_{DS} =0V, V_{GS} = ±12V			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ $I_{D}=-250\mu A$	-0.5	-0.9	-1.3	V
I _{D(ON)}	On state drain current	V _{GS} =-10V, V _{DS} =-5V	-27			Α
		V _{GS} =-10V, I _D =-4.0A		41	50	mΩ
D	Static Drain-Source On-Resistance	T _J =125℃		62	75	11122
R _{DS(ON)} Static Drain-So	Static Diam-Source On-Resistance	V _{GS} =-4.5V, I _D =-3.5A		47	60	mΩ
		V _{GS} =-2.5V, I _D =-2.5A		60	85	mΩ
g _{FS}	Forward Transconductance	V _{DS} =-5V, I _D =-4.0A		17		S
V_{SD}	Diode Forward Voltage	I _S =-1A,V _{GS} =0V		-0.7	-1	V
Is	Maximum Body-Diode Continuous Curr			-2	Α	
DYNAMIC	PARAMETERS					
C _{iss}	Input Capacitance			645		рF
C _{oss}	Output Capacitance	V _{GS} =0V, V _{DS} =-15 <mark>V, f</mark> =1MHz		80		pF
C _{rss}	Reverse Transfer Capacitance			55		pF
R_g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	4	7.8	12	Ω
SWITCHII	NG PARAMETERS	XX				
Q _g (10V)	Total Gate Charge			14		nC
Q _g (4.5V)	Total Gate Charge	10)/)/ 15)/ 1 404		7		nC
Q_{gs}	Gate Source Charge	-V _{GS} =-10V, V _{DS} =-15V, I _D =-4.0A		1.5		nC
Q_{gd}	Gate Drain Charge			2.5		nC
t _{D(on)}	Turn-On DelayTime			6.5		ns
t _r	Turn-On Rise Time	V_{GS} =-10V, V_{DS} =-15V, R_L =3.75 Ω ,		3.5		ns
t _{D(off)}	Turn-Off DelayTime	$R_{GEN}=3\Omega$		41		ns
t _f	Turn-Off Fall Time	1 1		9		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =-4.0A, dI/dt=100A/μs		11		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =-4.0A, dI/dt=100A/μs		3.5		nC

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The value in any given application depends on the user's specific board design.

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B. The power dissipation P_D is based on $T_{J(MAX)}$ =150°C, using \leq 10s junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C. Ratings are based on low frequency and duty cycles to keep initialT_J=25°C.

D. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300µs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedence which is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, assuming a maximum junction temperature of T_{J(MAX)}=150°C. The SOA curve provides a single pulse ratin g.



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 5: On-Resistance vs. Gate-Source Voltage

(Note E)

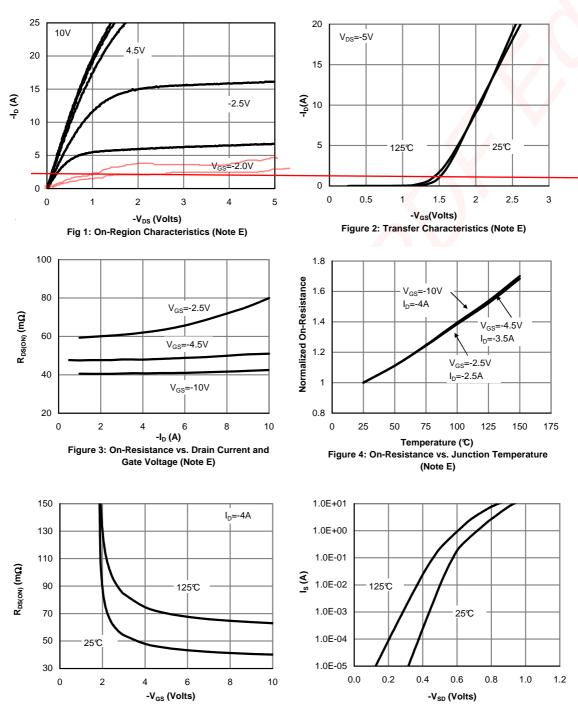


Figure 6: Body-Diode Characteristics (Note E)



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

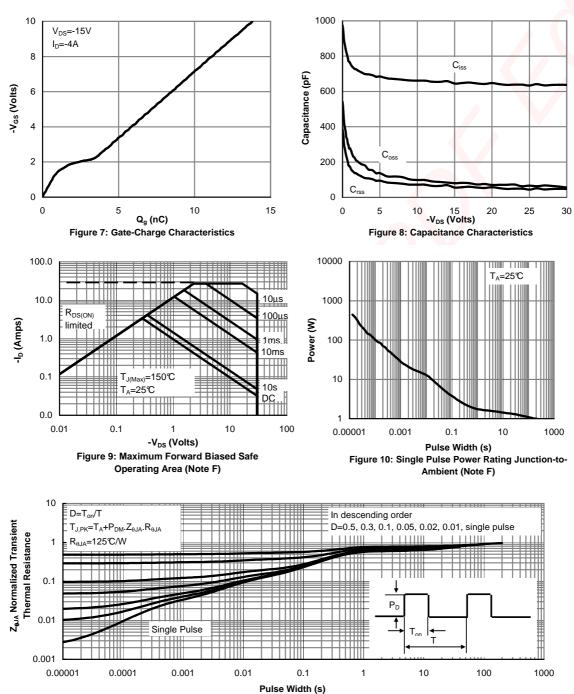
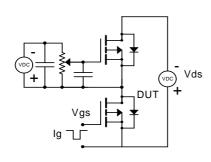
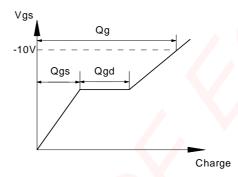


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

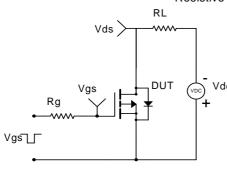


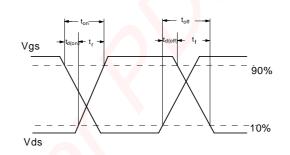
Gate Charge Test Circuit & Waveform



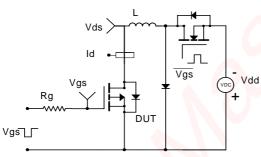


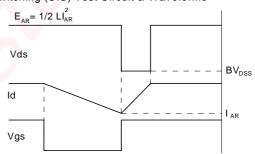
Resistive Switching Test Circuit & Waveforms





Unclamped Inductive Switching (UIS) Test Circuit & Waveforms





Diode Recovery Test Circuit & Waveforms

